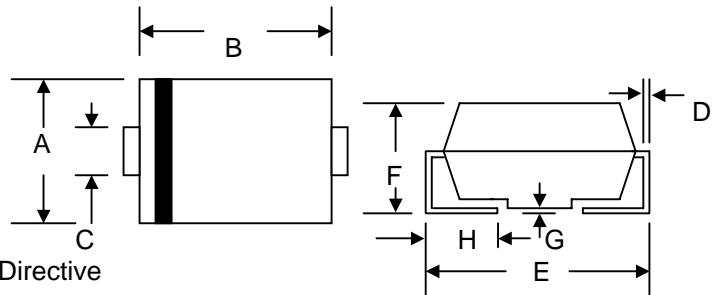


**Features**

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability
- Classification Rating 94V-O
- Green Products in Compliance with the RoHS Directive



**Mechanical Data**

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)

SMB/DO-214AA				
Dim	Min	Max	Min	Max
A	3.30	3.94	0.130	0.155
B	4.06	4.70	0.160	0.185
C	1.91	2.11	0.075	0.083
D	0.15	0.31	0.006	0.012
E	5.08	5.59	0.200	0.220
F	2.13	2.44	0.084	0.096
G	0.05	0.20	0.002	0.008
H	0.76	1.27	0.030	0.050
	In mm		In inch	

**Maximum Ratings and Electrical Characteristics** @ $T_A=25^{\circ}\text{C}$  unless otherwise specified

Characteristic	Symbol	SK22-G	SK23-G	SK24-G	SK25-G	SK26-G	SK28-G	SK29-G	S210-G	Unit	
Peak Repetitive Reverse Voltage	$V_{RRM}$	20	30	40	50	60	80	90	100	V	
Working Peak Reverse Voltage	$V_{RWM}$										
DC Blocking Voltage	$V_R$										
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	56	64	71	V	
Average Rectified Output Current @ $T_L = 105^{\circ}\text{C}$	$I_O$	2.0								A	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50								A	
Forward Voltage @ $I_F = 2.0\text{A}$	$V_{FM}$	0.55			0.70		0.85			V	
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	$I_{RM}$	0.5					20				mA
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{THJA}$	75								$^{\circ}\text{C/W}$	
Operating Temperature Range	$T_J$	-65 to +125								$^{\circ}\text{C}$	
Storage Temperature Range	$T_{STG}$	-65 to +150								$^{\circ}\text{C}$	

Note: 1. Mounted on P.C. Board with  $8.0\text{mm}^2$  copper pad areas

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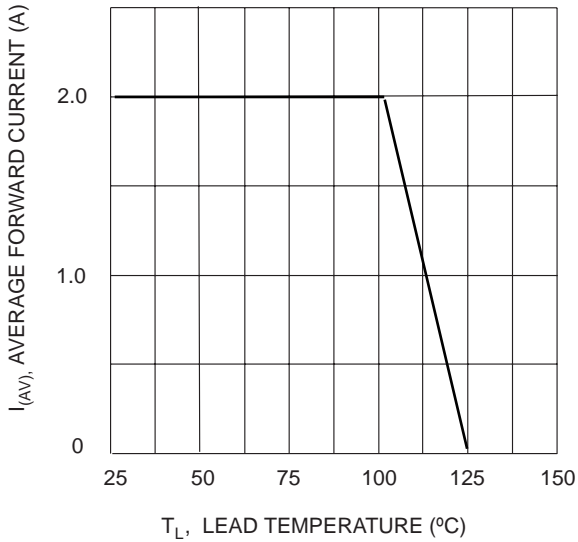


Fig. 1 Forward Current Derating Curve

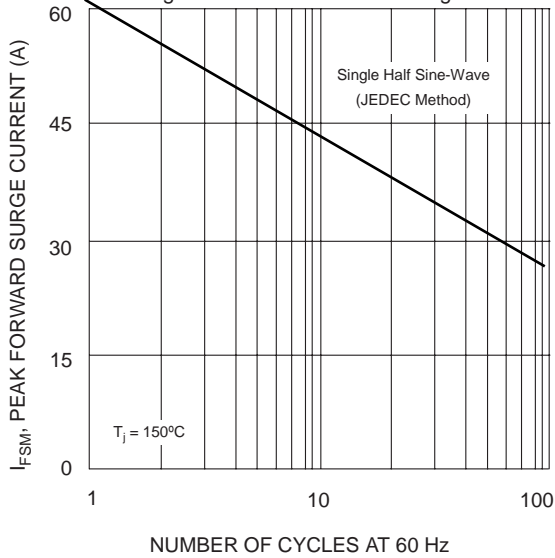


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

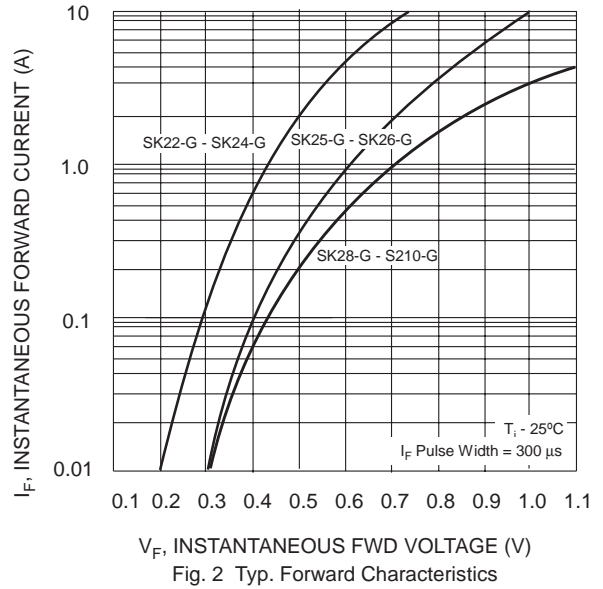


Fig. 2 Typ. Forward Characteristics

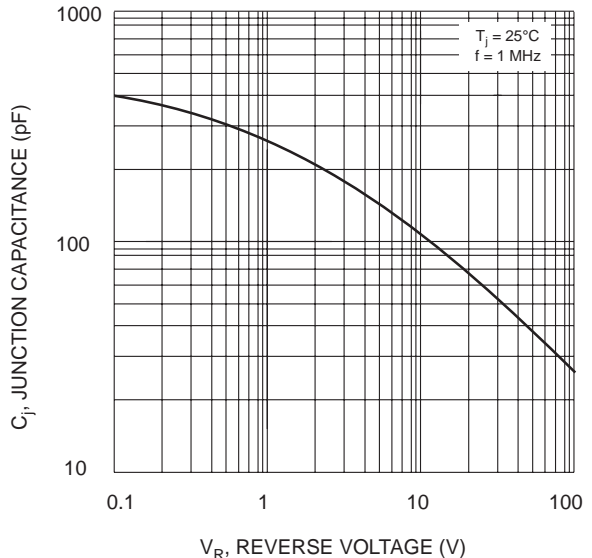


Fig. 4 Typical Junction Capacitance

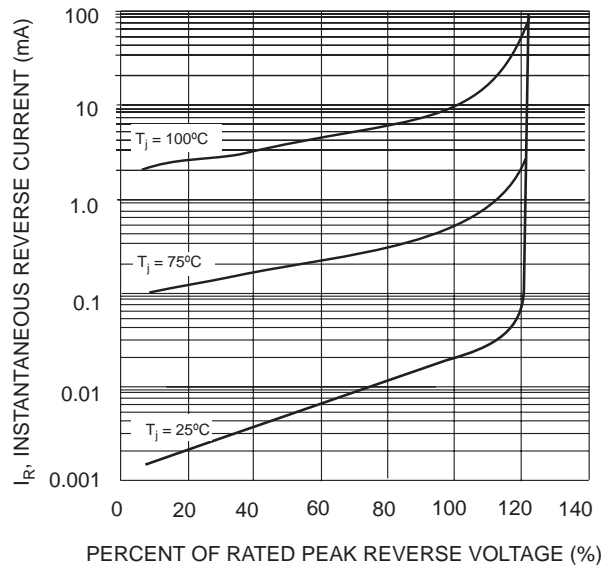


Fig. 5 Typical Reverse Characteristics

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